

BIPOLAR ANALOG INTEGRATED CIRCUIT μ PC4558

HIGH PERFORMANCE DUAL OPERATIONAL AMPLIFIER

DESCRIPTION

The μ PC4558 is a dual type operational amplifier having internal phase compensating circuits, its electrical characteristics features higher speed, broader bandwidth, and lower noise compared with such conventional general purpose operational amplifier as μ PC741.

Therefore, application to active filters, audio amplifiers, VCO, etc. can be realized with simple circuit composition.

FEATURES

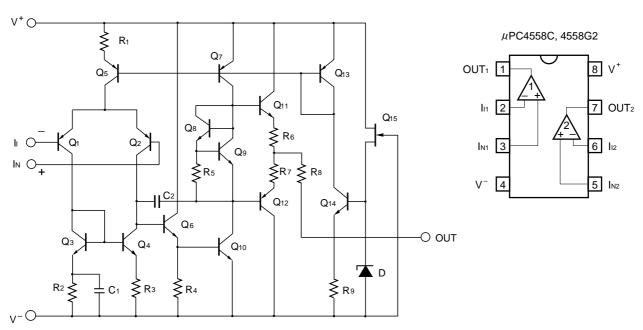
- Internal frequency compensation
- · Low noise
- · Output short circuit protection

ORDERING INFORMATION

	Part Number	Package
	μPC4558C	8-pin plastic DIP (7.62 mm (300))
	μPC4558G2	8-pin plastic SOP (5.72 mm (225))
*	μPC4558G2(5)	8-pin plastic SOP (5.72 mm (225))

EQUIVALENT CIRCUIT (1/2 Circuit)

PIN CONFIGURATION (Top View)



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ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Parameter		Symbol	Ratings	Unit
Voltage between V ⁺ and V ^{− Note 1}		V* - V	-0.3 to +36	V
Differential Input Volta	age	VID	±30	V
Input Voltage Note 2		Vı	V⁻–0.3 to V⁺ +0.3	V
Output Voltage Note 3		Vo	V⁻–0.3 to V⁺ +0.3	V
Power Dissipation C Package Note 4		Рт	350	mW
	G2 Package Note 5		440	mW
Output Short Circuit Duration Note 6			Indefinite	sec
Operating Ambient Temperature		TA	−20 to +80	°C
Storage Temperature		T _{stg}	-55 to +125	°C

- **Notes 1.** Reverse connection of supply voltage can cause destruction.
 - 2. The input voltage should be allowed to input without damage or destruction. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The normal operation will establish when the both inputs are within the Common Mode Input Voltage Range of electrical characteristics.
 - 3. This specification is the voltage which should be allowed to supply to the output terminal from external without damage or destructive. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The output voltage of normal operation will be the Output Voltage Swing of electrical characteristics.
 - 4. Thermal derating factor is -5.0 mV/°C when operating ambient temperature is higher than 55°C.
 - 5. Thermal derating factor is -4.4 mV/°C when operating ambient temperature is higher than 25°C.
 - **6.** Pay careful attention to the total power dissipation not to exceed the absolute maximum ratings, Note 4 and Note 5.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V [±]	±4		±16	V



μ PC4558C, μ PC4558G2

ELECTRICAL CHARACTERISTICS (T_A = 25°C, V^{\pm} = ±15 V)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Input Offset Voltage	Vio	Rs ≤ 10 Ω		±0.5	±6.0	mV
	Input Offset Current Note	lio			±5	±200	nA
	Input Bias Current Note	Ів			60	500	nA
	Large Signal Voltage Gain	Av	$R_L \ge 2 \ k\Omega$, $V_0 = \pm 10 \ V$	20,000	100,000		
₹	Power Consumption	Pd	Io = 0 A		90	170	mW
	Common Mode Rejection Ratio	CMR	Rs ≤ 10 kΩ	70	90		dB
	Source Variation Rejection Ratio	SVR	Rs ≤ 10 kΩ		30	150	μV/V
	Output Voltage Swing	Vom	$R_L \ge 10 \text{ k}\Omega$	±12	±14		V
			$R_L \ge 2 \ k\Omega$	±10	±13		V
	Common Mode Input Voltage Range	VICM		±12	±14		V
	Slew Rate	SR	Av = 1		1.0		V/μs
	Input Equivalent Noise Voltage	Vn	Rs = 1 k Ω , f = 1 Hz to 1 kHz (Figure 1)		6		μV _{p-p}
	Channel Separation		f = 1 kHz (Figure2)		105		dB

Note Input bias currents flow out from IC, because each currents are base current of PNP-transistor on input stage.

When using these ICs, pay careful attention to the following points.

- 1. The total of the internal power dissipation, when the loads of both channels are short-circuited at the same time.
- 2. The likelihood of interference between the channels, due to the temperature gradient of the chip, when the internal power dissipation of the left and right channels differ greatly in circuits handling low level inputs.

μ PC4558G2 (5) ELECTRICAL CHARACTERISTICS (T_A = 25°C, V[±] = ±15 V)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Input Offset Voltage	Vio	Rs ≤ 10 Ω		±0.5	±2.0	mV
	Input Offset Current Note	lio			±5	±50	nA
	Input Bias Current Note	Ів			60	100	nA
	Large Signal Voltage Gain	Av	$R_L \geq 2~k\Omega$, $V_0 = \pm 10~V$	50,000	100,000		
*	Power Consumption	Pd	Io = 0 A		90	135	mW
	Common Mode Rejection Ratio	CMR	Rs ≤ 10 kΩ	85	90		dB
	Source Variation Rejection Ratio	SVR	Rs ≤ 10 kΩ		30	75	μV/V
	Output Voltage Swing	Vom	$R_L \ge 10 \text{ k}\Omega$	±12.5	±14		V
			$R_L \ge 2 \ k\Omega$	±11	±13		V
	Common Mode Input Voltage Range	VICM		±13	±14		٧
	Slew Rate	SR	Av = 1		1.0		V/μs
	Input Equivalent Noise Voltage	Vn	Rs = 1 k Ω , f = 1 Hz to 1 kHz (Figure1)		6		μV_{p-p}
	Channel Separation		f = 1 kHz (Figure2)		105		dB

Note Input bias currents flow out from IC, because each currents are base current of PNP-transistor on input stage.

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- 1. The total of the internal power dissipation, when the loads of both channels are short-circuited at the same time.
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3

MEASUREMENT CIRCUIT

Figure 1 Noise Measurement Circuit

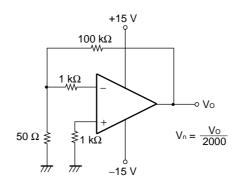
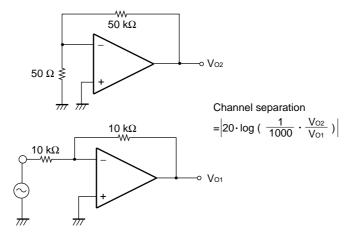
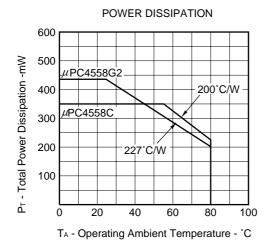
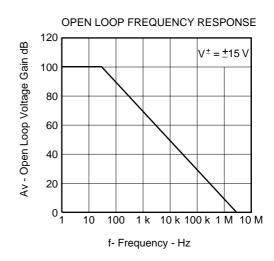


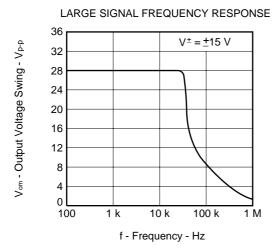
Figure2 Channel Separation Measurement Circuit

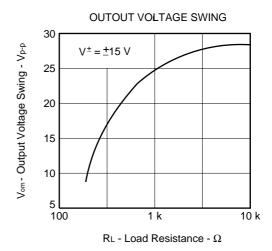


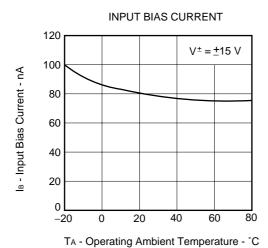
TYPICAL PERFORMANCE CHARACTERISTICS (TA = 25°C, TYP.)

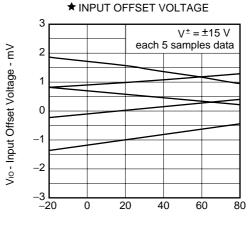


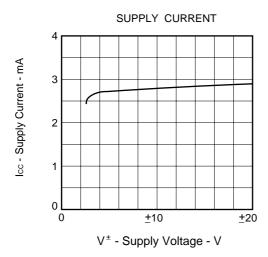


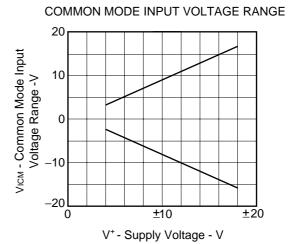




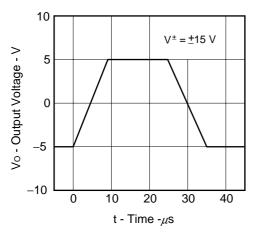




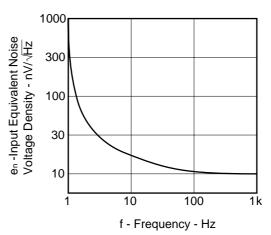




VOLTAGE FOLLOWER PULSE RESPONSE

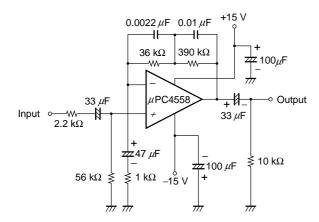


INPUT EQUIVALENT NOISE VOLTAGE DENSITY



APPLICATION CIRCUIT

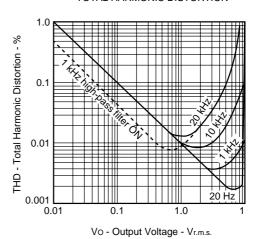
RIAA PREAMP (Av = 32.5 dB)



TYPICAL CHARACTERISTIC
Distortion 0.03% (Vo = 1Vr.m.s., f = 1 kHz)

Noise 1.0 μ V_{r.m.s.} (Input Equiv., Input Short Peak DEt., Average Indication)

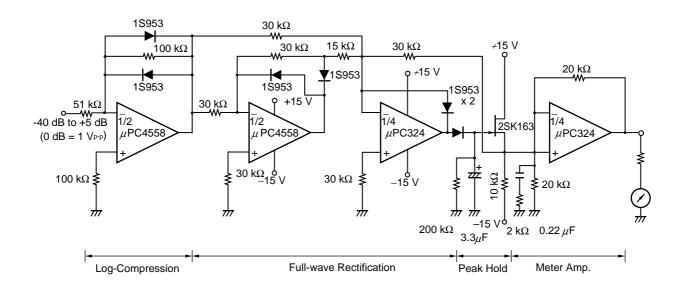




PEAK LEVEL METER

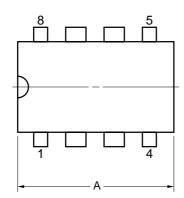
This circuit converts the peak voltage (about \pm 10 mV to \pm 10 V) of the input signal to a DC voltage (about 0.2 V to 1.3 V) and drives the meter.

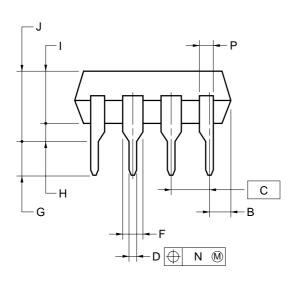
Since the output voltage is proportional to the logarithmic value of the peak voltage of the input signal, indication of a much wider dynamic range can be obtained compared to conventional linear indicating methods.

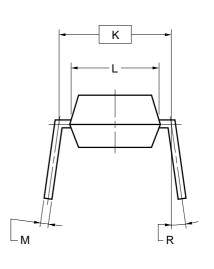


PACKAGE DRAWINGS (Unit: mm)

8-PIN PLASTIC DIP (7.62mm(300))







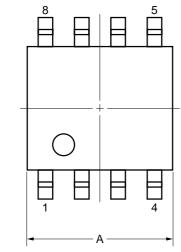
NOTES

- 1. Each lead centerline is located within 0.25 mm of its true position (T.P.) at maximum material condition.
- 2. Item "K" to center of leads when formed parallel.

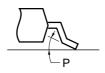
ITEM	MILLIMETERS
Α	10.16 MAX.
В	1.27 MAX.
С	2.54 (T.P.)
D	0.50±0.10
F	1.4 MIN.
G	3.2±0.3
Н	0.51 MIN.
I	4.31 MAX.
J	5.08 MAX.
K	7.62 (T.P.)
L	6.4
М	$0.25^{+0.10}_{-0.05}$
N	0.25
Р	0.9 MIN.
R	0~15°
	28C-100-300B C-2

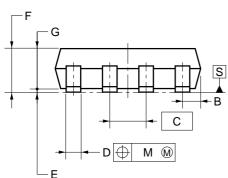
P8C-100-300B,C-2

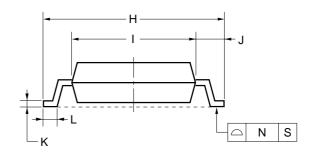
8-PIN PLASTIC SOP (5.72 mm (225))



detail of lead end







NOTE

Each lead centerline is located within 0.12 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
А	5.2 ^{+0.17} _{-0.20}
В	0.78 MAX.
С	1.27 (T.P.)
D	$0.42^{+0.08}_{-0.07}$
Е	0.1±0.1
F	1.59±0.21
G	1.49
Н	6.5±0.3
I	4.4±0.15
J	1.1±0.2
K	$0.17^{+0.08}_{-0.07}$
L	0.6±0.2
М	0.12
N	0.10
Р	3°+7°

S8GM-50-225B-6

★ RECOMMENDED SOLDERING CONDITIONS

The μ PC4558 should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

Type of Surface Mount Device

μPC4558G2: 8-pin plastic SOP (5.72 mm (225))

Process	Conditions	Symbol
Infrared Ray Reflow	ay Reflow Peak temperature: 230°C or below (Package surface temperature),	
	Reflow time: 30 seconds or less (at 210°C or higher),	
	Maximum number of reflow processes: 1 time.	
Vapor Phase Soldering	Peak temperature: 215°C or below (Package surface temperature),	VP15-00-1
	Reflow time: 40 seconds or less (at 200°C or higher),	
	Maximum number of reflow processes: 1 time.	
Wave Soldering	Solder temperature: 260°C or below, Flow time: 10 seconds or less,	WS60-00-1
	Maximum number of flow processes: 1 time,	
	Pre-heating temperature: 120°C or below (Package surface temperature).	
Partial Heating Method	Heating Method Pin temperature: 300°C or below,	
	Heat time: 3 seconds or less (Per each side of the device).	

Caution Apply only one kind of soldering condition to a device, except for "partial heating method", or the device will be damaged by heat stress.

Type of Through-hole Device

μPC4558C: 8-pin plastic DIP (7.62 mm (300))

Process	Conditions
Wave Soldering Solder temperature: 260°C or below,	
(only to leads) Flow time: 10 seconds or less.	
Partial Heating Method Pin temperature: 300°C or below,	
	Heat time: 3 seconds or less (per each lead).

Caution For through-hole device, the wave soldering process must be applied only to leads, and make sure that the package body does not get jet soldered.

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